Minutes
Multi-Gigabit Optical Automotive Ethernet (OMEGA)
Task Force Interim
29 June 2021

Attendance list as recorded in Webex participant list

Last Name	First Name	Employer	Affiliations	June 29th
Abbott	John	Corning	Corning	X
Amamiya	Yasushi	MegaChips	MegaChips	
Andrae	Stefan	SEI Antech-Europe GmbH	SEI Antech-Europe GmbH	
Aono	Michikazu	Yazaki	Yazaki	
Araki	Nobuyasu	Yazaki	Yazaki	
Bergner	Bert	TE Connectivity	TE Connectivity	
Boyer	Rich	APTIV	APTIV	
Barbero	Fernando	KDPOF	KDPOF	X
Bordogna	Mark	Intel	Intel	
Brooks	Paul	Viavi Solutions	Viavi Solutions	
Bruckman	Leon	Huawei	Huawei	
Chang	Jae-yong	Keysight	Keysight	
Choudhury	Mabud	OFS	OFS	X
Chuang	Keng Hua	HPE	HPE	
Cuesta	Emilio	TE Connectivity	TE Connectivity	X
Dittmann	Markus	KDPOF	KDPOF	
Donthu	Suresh	Corning	Corning	
Eek	Magnus	Volvo Cars	Volvo Cars	
Felgenhauer	Alexander	Yazaki	Yazaki	
Ferretti	Vincent	Corning	Corning	
Fortusini	David	Corning	Corning	
Fukuoka	Takashi	AutoNetworks Technologies Ltd.	AutoNetworks Technologies Ltd.; Sumitomo Electric Industries, Ltd.	X
Giovanne	Laura	Broadcom	Broadcom	
Glanzner	Martin	SEI Antech-Europe GmbH	SEI Antech-Europe GmbH	
Gomez	Chisato	Nitto Denko Corporation	Nitto Denko Corporation	X
Goto	Hideki	Toyota Motor Corporation	Toyota Motor Corporation	
Grow	Robert	Robert M. Grow Consulting	RMG Consulting, KDPOF	X
Hajduczenia	Marek	Charter Communications	Charter Communications	
Harshbarger	Douglas	Corning Incorporated	Corning Incorporated	
Hartmann	Stephan	Siliconally GmbH	Siliconally GmbH	
Hayashi	Takehiro	HAT Labs	HAT Labs	X
HIRASE	Hidenari	AGC	AGC	
Horrmeyer	Bernd	Phoenix Contact	Phoenix Contact	
Huang	David	Broadcom	Broadcom	
Huang	Shaowu	Marvell	Marvell	
Hyakutake	Yasuhiro	Adamant Namiki Precision Jewel	Adamant Namiki Precision Jewel	X
Isono	Hideki	FOC	FOC	X
Kadry	Haysam	Ford Motor Company	Ford Motor Company	
KAGAMI	Manabu	NI Tech	NI Tech	X
Kazuhiko	Ishibe	Anritsu	Anritsu	
Kamino	John	OFS	OFS	
Kawahara	Keisuke	Furukawa Electric	Furukawa Electric	X
KIKUTA	Tomohiro	Adamant Namiki Precision Jewel	Adamant Namiki Precision Jewel	X
Kim	Joshua	Hirose USA	Hirose USA	
King	Roger	TRUMPF Photonic Components	TRUMPF Photonic Components	X

Kobayashi	Shigeru	AIO Core	AIO Core	X
Koeppendoerfer	Erwin	Leoni	Leoni	X
Kondo	Taiji	MegaChips	MegaChips	X
Law	David	HPE	HPE	
Lewis	David	Lumentum	Lumentum	
Liu	Karen	Lightwave	Lightwave	
Lee	Bernard	Senko	Senko	
Lee	Sylvanus	Leviton	Leviton	
Lingle	Robert	OFS	OFS	
Malicoat	David	Malicoat Networking Solutions	Senko Advanced Components	X
Martino	Kjersti	Inneos	Inneos	
Marques	Flavio	Furukawa electric	Furukawa Electric	
Masuda	Takeo	OITDA/PETRA	OITDA/PETRA	
McMillan	Larry	Western Digital	Western Digital	
Mueller	Harald	Endress + Hauser	Endress + Hauser	
Mueller	Thomas	Rosenberger	Rosenberger	
Murty	Ramana	Broadcom	Broadcom	X
Nakagawa	Hideki	AGC	AGC	X
New	Anthony	Prysmian Group	Prysmian Group	
Nicholl	Gary	Cisco	Cisco	
Nikolich	Paul	802 Chairman	802 Chairman	
Niihara	Yoshihiro	Fujikura	Fujikura	X
Ogura	Ichiro	Petra	Petra	X
Omori	Kumi	NEC	NEC	
Ortiz	David	KDPOF	KDPOF	
Pandey	Sujan	Huawei	Huawei	
Pankert	Joseph	TRUMPF Photonic Components	TRUMPF Photonic Components	X
Pardo	Carlos	KDPOF	KDPOF	
Pérez-Aranda	Rubén	KDPOF	KDPOF	X
Pham	Phong	EastPoint	EastPoint	
Piehler	David	Dell	Dell	
Pimpinella	Rick	Panduit	Panduit	
Pinzón	Plinio	KDPOF	KDPOF	
Pitwon	Richard	Resolute Photonics	Resolute Photonics	X
Preis	Roland	MD Elektronik	MD Elektronik	X
Reinhard	Michael	SEI Antech-Europe GmbH	SEI Antech-Europe GmbH	
Sambasivan	Sam	AT&T	AT&T	
Savi	Olindo	Hubbell Incorporated	Hubbell Incorporated	
Sawano	Hiroshi	OITDA		
Sayre	Edward	Samtec	Samtec	
Shukla	Priyank	Synopsys	Synopsys	
Shigematsu	Masayuki	Sumitomo Electric	Sumitomo Electric	
Shiino	Masato	Furukawa Electric	Furukawa Electric	X
Shukla	Priyank	Synopsys	Synopsys	
Silvano de Sousa	Jonathan	GG-Group	GG-Group	X
Sun	Wensheng	Marvell	Marvell	
Sun	Yi	OFS	OFS	
Suzuki	Yasuo	KDPOF Japan	KDPOF	
Swanson	Steve	Corning Inc.	Corning Inc.	X
Takahashi	Ryutaro	Senko	Senko	X
Takahashi	Satoshi	POF Promotion	POF Promotion	
Takahashi	Tadashi	Nitto Denko Corporation	Nitto Denko Corporation	X
Takayama	Kazuya	Nitto Denko Corporation	Nitto Denko Corporation	X
Tan	I-Hsing	Broadcom	Broadcom	
Theuerkom	Thomas	Corning	Corning	
Theodoras	James	HG Genuine	HG Genuine	
Torres	Luisma	KDPOF	KDPOF	X

Tsujita	Yuichi	Nitto Denko Corporation	Nitto Denko Corporation	X
Tsuzaki	Nozomi	Independent	Independent	X
Ueno	Yuto	Sumitomo	Sumitomo	X
Walsh	Thomas	KDPOF	KDPOF	
WATANABE	Yuji	AGC	AGC	X
Wendt	Mattias	Signify	Signify	
Wienckowski	Natalie	General Motors	General Motors	
Wiesner	Michael	Trumpf	Trumpf	
Xu	Xing	Huawei	Huawei	X
Yamada	Osamu	Yazaki	Yazaki	
Yang	Yumeng	Huawei	Huawei	
Yasui	Hideshi	AGC	AGC	X
Yonemura	Masatoshi	NITech	NITech	X
Yonezawa	Kenji	AGC	AGC	X
Yurtin	John	APTIV	APTIV	
Zhiwei	Yang	ZTE	ZTE	
Zhu	Liang	Marvell	Marvell	

Tuesday, 29th June 2021, 12:00 (noon) UTC

The meeting was called to order at approximately 12:01 UTC Tuesday 29th June 2021
Chaired by Robert Grow, IEEE P802.3cz Task Force Chair.

Mr. Grow presented *Agenda and General Information* (https://www.ieee802.org/3/cz/public/29_jun_2021/Agenda_3cz_01_290621.pdf).

Mr. Grow presented the agenda for the meeting. The agenda was approved by unanimous consent.

Mr. Grow asked the audience if there was anybody from the press. No one responded to the call.

Mr. Grow issued the call for essential patent claims. No one responded to the call. He also presented the slides on the IEEE Copyright Policy and participation guidelines.

Mr. Pitwon asked to present *Status on silicon photonics reliability test* (https://www.ieee802.org/3/cz/public/29_jun_2021/ogura_3cz_01_290621_Status_SiPhotonicsReliabilityTest_v13.pdf). This presentation shows how Co-package optics and silicon photonics can be combined and an example of silicon photonics transceiver. The main difference compared with a VCSEL-based transceiver is that the QD-LD is driven with a bias current continuously, and the modulation is performed by another component (a MZ modulator). Single Mode Fiber (SMF) is needed to connect the QD-LD and the MZ modulation. The output of the MZ modulator is sent to a vertical grating coupler that excites the Multimode Fiber (MMF) that can be OM3 or GIPOF. This presentation also shows the QD-LD lifetime estimate for automotive mission profile and an 850nm and 980 nm VCSEL reliability comparison. Redundancy of components is proposed as a way for increased reliability. Many questions were made about Silicon Photonics maturity, cost comparison, complexity, power consumption, and remaining tasks in the ToDo list to be complete, and Mr. Pitwon provided responses.

Mr. Torres asked to start with the D1.1 comment resolution following the order in *Chief Editor's Report* (https://www.ieee802.org/3/cz/public/8_jun_2021/CEReport_3cz_080621.pdf). Buckets 1, 2, 3, 4 and 5, with a total of 44 comments, were discussed and resolved.

Mr. Grow wrapped up the teleconference with the last slides of *Agenda and General Information* (https://www.ieee802.org/3/cz/public/22_jun_2021/Agenda_3cz_01_220621.pdf). Mr. Grow asked the participants about the number of TF meetings to be held in July. After reviewing the expected presentations in the ToDo list (https://www.ieee802.org/3/cz/P802_3cz_todo_01k_250521.xlsm) , it was decided to maintain the four proposed days (13, 14, 20 and 21 July) during the upcoming plenary session.

The meeting was adjourned at approximately 14:04 UTC.